

PART INFORMATION		
Mfg Item Number		MCIMX6DP5EYM1AB
Mfg Item Name		624 21*21*1.45 P0.8
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2018-04-17
Response Document ID		00MEK00239D001M1.0
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
Contact Phone		1-800-521-6274
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Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
Representative Phone		512-895-3406
Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		Yes
Pb Free		Yes
HalogenFree		Yes
Plating Indicator		e1
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number		MCIMX6DP5EYM1AB
Mfg Item Name		624 21*21*1.45 P0.8
Version		ALL
Weight		1.178100
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		3
Peak Processing Temperature		260 C
Max Time at Peak Temperature		40 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Underfill	0.0147						g					
Underfill		Solvents, additives, and other materials	4,4'-Diamino-3,3'-diethyl-diphenylmethane	19900-65-3		0.001617	g	110000	11		1372	0.1372
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1		0.0000147	g	1090	0.1		12	0.0012
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.0001176	g	8000	0.8		99	0.0099
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.002058	g	140000	14		1746	0.1746
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00147	g	100000	10		1247	0.1247
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0000147	g	1090	0.1		12	0.0012
Underfill		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.000588	g	40000	4		499	0.0499
Underfill		Glass	Silica, vitreous	60676-86-0		0.00862	g	600000	60		7486	0.7486
Solder Balls - Lead Free	0.3024						g					
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.01374559	g	45455	4.5455		11667	1.1667
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.00896435	g	29644	2.9644		7609	0.7609
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.27969006	g	924901	92.4901		237407	23.7407
Organic Substrate, Halogen-free	0.8121						g					
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.01199959	g	14776	1.4776		10185	1.0185
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.38333556	g	472030	47.203		325400	32.54
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 862	28964-14-4		0.068109	g	71554	7.1554		49324	4.9324
Organic Substrate, Halogen-free		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4		0.01859059	g	22892	2.2892		15780	1.578
Organic Substrate, Halogen-free		Lead/Lead Compounds	Lead	7439-92-1		0.00007065	g	87	0.0087		59	0.0059
Organic Substrate, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.031732	g	39074	3.9074		26934	2.6934
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.19435746	g	239327	23.9327		164975	16.4975
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.01665942	g	20514	2.0514		14140	1.414
Organic Substrate, Halogen-free		Metals	Tin, metal	7440-31-5		0.00012344	g	152	0.0152		104	0.0104
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.0019263	g	2372	0.2372		1635	0.1635
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-51-2		0.09519599	g	117222	11.7222		80804	8.0804
Pb-free Bumped Semiconductor D	0.0489						g					
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.0002445	g	5000	0.5		207	0.0207
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.00015404	g	3150	0.315		130	0.013
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00424697	g	86850	8.685		3604	0.3604
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.0004401	g	9000	0.9		373	0.0373
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.04381439	g	896000	89.6		37190	3.719

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MCIMX6DP5EYM1AB_IPC1752_v11.xml

http://www.freescale.com/mcds/MCIMX6DP5EYM1AB_IPC1752A.xml